RELIABILITY REPORT

FOR

MAX4707EXK+

PLASTIC ENCAPSULATED DEVICES

July 24, 2012

MAXIM INTEGRATED PRODUCTS

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Approved by
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Conclusion

The MAX4707EXK+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX4706/MAX4707 single-pole/single-throw (SPST) switches operate from a single 1.8V to 5.5V supply. The MAX4706 is a normally closed (NC) switch and the MAX4707 is the normally open (NO) version. These switches provide 2 on-resistance (RON) and 0.6 RON flatness with a +2.7V supply. These devices typically consume only 0.02µA of quiescent current, making them suitable for use in low-power, portable applications. The MAX4706/MAX4707 feature low-leakage currents over the entire temperature range, TTL/CMOS-compatible digital logic, and excellent AC characteristics. The MAX4706/MAX4707 are offered in small 5-pin and 6-pin SC70 and 6-pin µDFN packages.

II. Manufacturing Information

A. Description/Function:	Low-Voltage, 2 , SPST, CMOS Analog Switches
B. Process:	E35
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	Malaysia, Thailand
F. Date of Initial Production:	January 23, 2004

III. Packaging Information

A. Package Type:	5L SC70
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0833 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	324°C/W
K. Single Layer Theta Jc:	115°C/W
L. Multi Layer Theta Ja:	324°C/W
M. Multi Layer Theta Jc:	115°C/W

IV. Die Information

A. Dimensions:	28 X 31 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.35µm
F. Minimum Metal Spacing:	0.35µm
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 126 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 8.7 \times 10^{-9}$

$\lambda = 8.7$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the E35 Process results in a FIT Rate of 0.68 @ 25C and 11.68 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot CJN1AQ001C D/C 0349)

The AS19-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX4707EXK+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48 78	0 0	DJN4CQ003A, DC 0613 CJN4AQ003B, DC 0414

Note 1: Life Test Data may represent plastic DIP qualification lots.